

Silicon P Channel MOS Type ( -MOS )

TENTATIVE

# SSM6K31FE

High speed switching  
DC-DC Converter

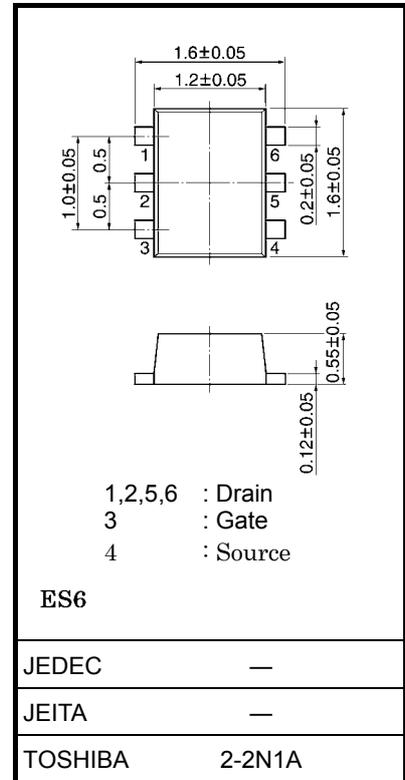
Unit: mm

- small package
- Low R<sub>DS</sub> (ON) : R<sub>on</sub> = 240 mΩ (typ) (@V<sub>GS</sub> = 10 V)  
: R<sub>on</sub> = 400 mΩ (typ) (@V<sub>GS</sub> = 4 V)

### Maximum Ratings (Ta = 25°C) MOSFET

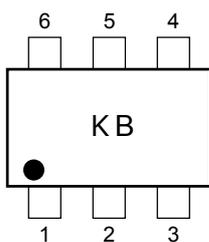
Characteristics		Symbol	Rating	Unit
Drain-Source voltage		V <sub>DS</sub>	20	V
Gate-Source voltage		V <sub>GSS</sub>	±20	V
Drain current	DC	I <sub>D</sub>	1.2	A
	Pulse	I <sub>DP</sub>	2.4	
Drain power dissipation		P <sub>D</sub> (Note 1)	500	mW
Channel temperature		T <sub>ch</sub>	150	°C
Storage temperature		T <sub>stg</sub>	-55~150	°C

Note 1: Mounted on FR4 board  
(25.4 mm × 25.4 mm × 1.6 t, Cu pad: 645 mm<sup>2</sup>)

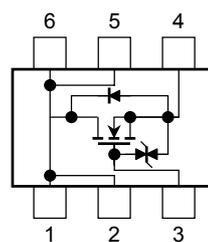


Weight: 3 mg (typ.)

### Marking Circuit (top view)



### Equivalent



### Handling Precaution

When handling individual devices (which are not yet mounting on a circuit board), be sure that the environment is protected against electrostatic discharge. Operators should wear anti-static clothing and use containers and other objects that are made of anti-static materials.

The Channel-to-Ambient thermal resistance R<sub>th</sub> (ch-a) and the drain power dissipation P<sub>D</sub> vary according to the board material, board area, board thickness and pad area. When using this device, please take heat dissipation fully into account.

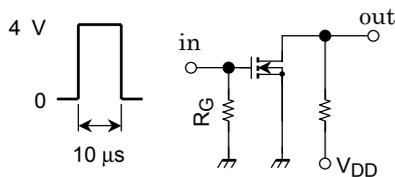
## Electrical Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	$I_{GSS}$	$V_{GS} = \pm 16\text{ V}, V_{DS} = 0$	–	–	$\pm 1$	$\mu\text{A}$
Drain-Source breakdown voltage	$V_{(BR)DSS}$	$I_D = 1\text{ mA}, V_{GS} = 0$	20	–	–	V
	$I_{DSS}$	$V_{DS} = 20\text{ V}, V_{GS} = 0$	–	–	1	$\mu\text{A}$
Drain Cut-off current	$V_{th}$	$V_{DS} = 5\text{ V}, I_D = 0.1\text{ mA}$	1.1	–	2.3	V
Gate threshold voltage	$ Y_{fs} $	$V_{DS} = 5\text{ V}, I_D = 0.6\text{ A}$ (Note 2)	0.58	–	–	S
Forward transfer admittance	$R_{DS(ON)}$	$I_D = 0.6\text{ A}, V_{GS} = 10\text{ V}$ (Note 2)	–	240	320	m $\Omega$
Drain-Source ON resistance		$I_D = 0.6\text{ A}, V_{GS} = 4\text{ V}$ (Note 2)	–	400	540	
	$C_{iss}$	$V_{DS} = 10\text{ V}, V_{GS} = 0, f = 1\text{ MHz}$	–	36	–	pF
Input capacitance	$C_{rss}$	$V_{DS} = 10\text{ V}, V_{GS} = 0, f = 1\text{ MHz}$	–	10	–	pF
Reverse transfer capacitance	$C_{oss}$	$V_{DS} = 10\text{ V}, V_{GS} = 0, f = 1\text{ MHz}$	–	30	–	pF
Switching time	Turn-on time	$V_{DD} = 10\text{ V}, I_D = 0.6\text{ A},$ $V_{GS} = 0 \sim 4\text{ V}, R_G = 10\ \Omega$	–	–	–	ns
	Turn-off time		–	–	–	

Note 2: Pulse measurement

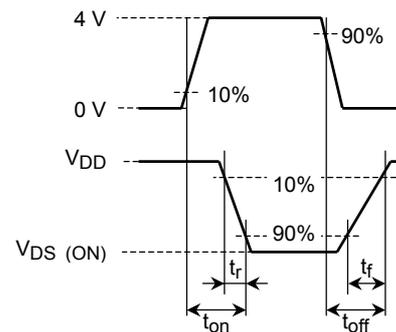
## Switching Time Test Circuit

### (a) Test circuit

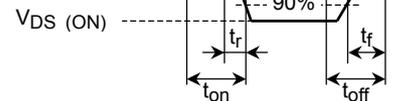


$V_{DD} = 10\text{ V}$   
 $R_G = 10\ \Omega$   
 Duty  $\leq 1\%$   
 $V_{IN}$ :  $t_r, t_f < 5\text{ ns}$   
 Common source  
 $T_a = 25^\circ\text{C}$

### (b) $V_{IN}$



### (c) $V_{OUT}$



## Precaution

$V_{th}$  can be expressed as voltage between gate and source when low operating current value is  $I_D = 100\ \mu\text{A}$  for this product. For normal switching operation,  $V_{GS(on)}$  requires higher voltage than  $V_{th}$  and  $V_{GS(off)}$  requires lower voltage than  $V_{th}$ .

(Relationship can be established as follows:  $V_{GS(off)} < V_{th} < V_{GS(on)}$ )

Please take this into consideration for using the device.

$V_{GS}$  recommended voltage of 4.0 V or higher to turn on this product.

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